SONY SI-F130 SMT Pick And Place Machine 25900 CPH High Precision

Our Product Introduction

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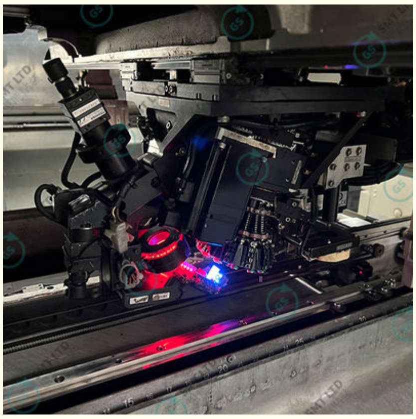
Basic Information

Place of Origin:	Japan
Brand Name:	SONY
Model Number:	SI-F130
Minimum Order Quantity:	1 PCS
Price:	USD+negotiable+pcs
Packaging Details:	1500mm*1600mm*1750mm
Delivery Time:	1-7 days
Payment Terms:	T/T
Supply Ability:	1+pcs+per days

Product Specification

Equipment Model:	SI-F130
Soldering Head:	1 Head & 12 Nozzles
Feeder Quantity:	50
Vision System:	Optical Recognition System
Component Size:	Max: 6mm
Soldering Accuracy:	50um (CPK 1.0 Or Above)
PCB Size:	50mm*50mm - 360mm*1200mm
Component Thickness:	0402 (01005) - 12mm IC (mobile Camera) 6mm - 25mm IC (fixed Camera)
PCB Thickness:	0.5mm To 2.6mm
Operating Environment:	Ambient Temperature 15 ~30 , Environmental Humidity 30%~70% (no Condensation Allowed)
Working Noise:	35-65 Decibels
Correction Method:	Machine Vision System, Multi-point MARK Vision Correction



More Images

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Key Specifications

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Correction Method	Machine vision system, multi-point MARK vision correction
Drive System	AC servo, AC motor
Data Transmission	USB interface input (EXCEL document format)
Operating System	Chinese, English, Japanese interface (WINDOWS system control platform)
Control Mode	Fully automatic
Soldering Speed	0.139 seconds (25900 CPH)
Equipment Dimensions (W×D×H)	1220mm × 1400mm × 1545mm
Equipment Weight	1560KG

Product Highlights

High-speed placement capability: **25,900 CPH** (0.139 seconds per chip)

Advanced **CCD camera** with unique image recognition system for precise component identification

Globally unique **rotating planetary type mounting head** with 12 suction nozzles

Exceptional mounting accuracy of **50μm** with CPK 1.0 or above

Compact footprint with **low power consumption** and minimal noise (35-65 dB)

Ideal for high-speed surface mounting of **1.2-meter LED light beads**

Multi-language interface (Chinese, English, Japanese) on Windows control platform

Technical Description

The SONY 130 series surface mounters, including the F130 model, represent high-quality SMT equipment with exceptional performance. Featuring a planetary-type mounting head with 12 suction nozzles, these machines deliver both speed and precision. The optical recognition system ensures accurate component placement, while the compact design offers space efficiency without compromising on capability. With its fully automatic control mode and versatile PCB handling, the SI-F130 is particularly well-suited for LED light bead applications and other high-speed surface mounting requirements.

Room F3B-016, B Block, Hao Yun Lai Bussiness Building, Liutang road , Bao'an District , Shenzhen, China